

**S/N Unknown**

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Nick A. Youker et al.

Examiner: Unknown

Serial No.: Unknown

Group Art Unit: Unknown

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Title: INTEGRATED EMI SHIELD UTILIZING A HYBRID EDGE

**PRELIMINARY AMENDMENT**

**BOX PATENT APPLICATION**

Commissioner for Patents

Washington, D.C. 20231

Sir:

Please amend the above-identified patent application as follows:

**IN THE SPECIFICATION**

On page 1, line 3, before the heading, "Technical Field", insert the following paragraph:

**-- Cross Reference to Related Application(s)**

This application is a division of U.S. Patent Application No. 09/378,407, filed on August 20, 1999, the specification of which is incorporated herein by reference. --

Please substitute the following paragraphs of the Specification with the paragraphs in the appendix entitled Clean Version of Specification Paragraphs. Following are marked-up versions of the amended paragraphs showing specific changes:

Specific amendments to the paragraph beginning on page 6, line 2, are as follows:

FIG. 5 illustrates various views of an embodiment of chip carrier 530. FIG. 5A is a top view of one embodiment of a chip carrier. IC chip carriers 530 may incorporate a cavity 518 that holds integrated circuit chips or other circuits. [FIG. 5B] FIG. 5C illustrates the chip carrier 530 cross-section showing the staircase-shaped steps 550 of cavity 518. Other cavities may not have this structure as is illustrated by a second cavity 519. As shown in FIG. 5A, patterned electrical conductors terminating in bonding pads 522 lie on the surfaces of the ceramic layers and on the steps 550 of cavity 518. The bonding pads 522 on the cavity steps 550 are connected to an